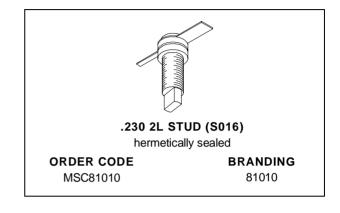
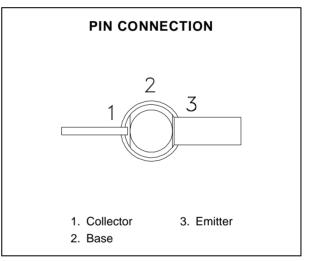


MSC81010

RF & MICROWAVE TRANSISTORS GENERAL PURPOSE AMPLIFIER APPLICATIONS

- EMITTER BALLASTED
- VSWR CAPABILITY ∞:1 @ RATED CONDITIONS
- HERMETIC STRIPAC[®] PACKAGE
- $P_{OUT} = 10$ W MIN. WITH 10 dB GAIN @ 1 GHz





DESCRIPTION

The MSC81010 is a common base hermetically sealed silicon NPN microwave transistor utilizing a fishbone, emitter ballasted geometry with a re-fractory/gold metallization system. This device is capable of withstanding infinite load VSWR at any phase angle under rated conditions.

The MSC81010 is designed for Class C amplifier applications in the 0.4 - 1.2 GHz frequency range.

ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}C$)

Symbol	Parameter	Value	Unit			
P _{DISS}	Power Dissipation*	29	W			
Ιc	Device Current*	1.0	А			
V _{CC}	Collector-Supply Voltage*	35	V			
TJ	Junction Temperature	200	°C			
T _{STG}	Storage Temperature	– 65 to +200	°C			

THERMAL DATA

	R _{TH(j-c)}	Junction-Case Thermal Resistance*	6.0	°C/W
*	Applies only to rated R	E amplifier operation		

*Applies only to rated RF amplifier operation

MSC81010

ELECTRICAL SPECIFICATIONS $(T_{case} = 25^{\circ}C)$

STATIC

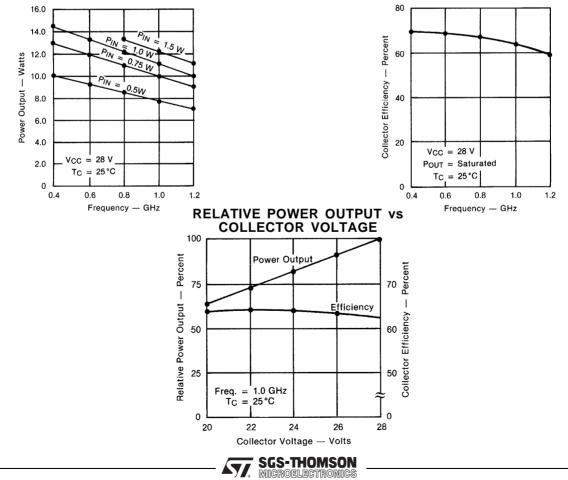
Symbol	Test Conditions	Value			11:0:4		
Symbol		Min.	Тур.	Max.	Unit		
BV _{CBO}	$I_C = 1mA$	$I_E = 0mA$		45	_		V
BV _{EBO}	$I_E = 1 m A$	$I_C = 0 m A$		3.5	_		V
BVCER	IC = 10mA	$R_{BE} = 10\Omega$		45	_		V
Ісво	$V_{CB} = 28V$					2.5	mA
hFE	$V_{CE} = 5V$	$I_C = 500 \text{mA}$		15	—	120	—

DYNAMIC

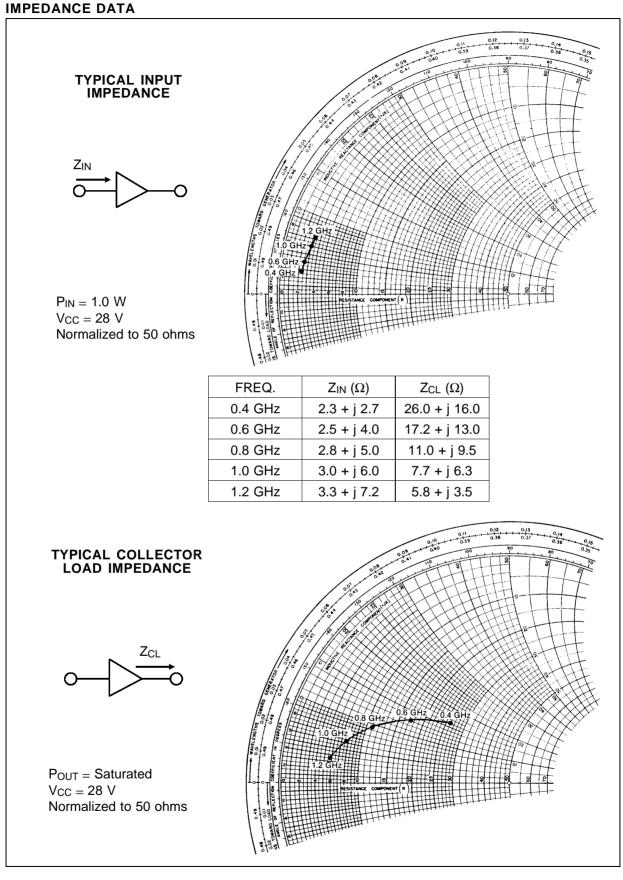
Symbol	ymbol Test Conditions		Value			Unit	
Symbol			Min.	Тур.	Max.	Unit	
Роит	f = 1.0 GHz	$P_{IN} = 1.0 W$	$V_{CC} = 28 V$	10	11		W
ηc	f = 1.0 GHz	$P_{IN} = 1.0 \text{ W}$	$V_{CC} = 28 V$	60	64		%
GP	f = 1.0 GHz	$P_{IN} = 1.0 \text{ W}$	$V_{CC}=28\ V$	10	10.4	—	dB
C _{OB}	f = 1 MHz	$V_{CB} = 28 V$		—	—	10	pF

TYPICAL PERFORMANCE POWER OUTPUT vs FREQUENCY

FREQUENCY vs COLLECTOR EFFICIENCY



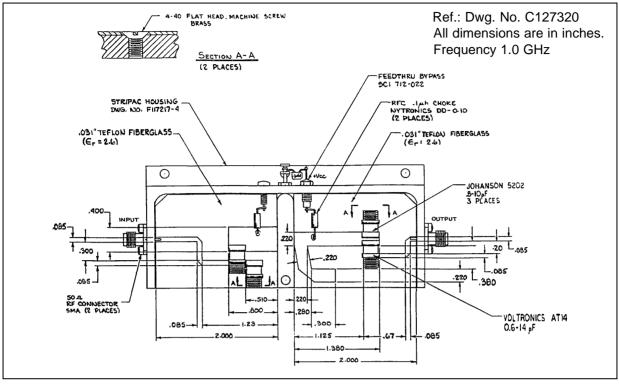
2/5



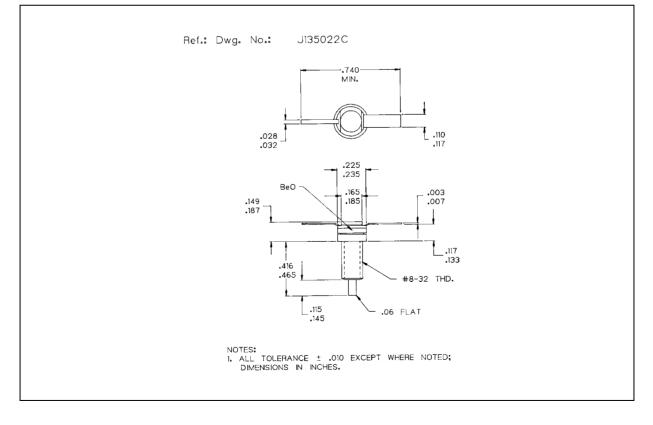
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MSC81010

TEST CIRCUIT



PACKAGE MECHANICAL DATA



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